

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
Suggested classification::
Suggested Group Art Unit::
CD-ROM or CD-R?:: None
Computer Readable Form (CRF)?:: No
Title:: WAFER HEAT-TREATMENT SYSTEM AND
WAFER HEAT-TREATMENT METHOD
Attorney Docket Number:: 025311-0115
Request for Early Publication?:: No
Request for Non-Publication?:: No
Suggested Drawing Figure:: 1
Total Drawing Sheets:: 3
Small Entity?:: No
Petition included?:: No
Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Japanese
Status:: Full Capacity
Given Name:: Yoshimasa
Family Name:: KAWASE
City of Residence:: Kanagawa
Country of Residence:: Japan

Street of mailing address:: c/o Semiconductor Leading Edge Technologies, Inc.
292 Yoshida-cho, Totsuka-ku, Yokohama
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Country of mailing address:: Japan

Correspondence Information

Correspondence Customer Number:: 22428

E-Mail address:: wellis@foleylaw.com

Representative Information

Representative Customer Number::	22428	
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	2001-036040	02/13/2001	Yes

Assignee Information

Assignee name:: SEMICONDUCTOR LEADING EDGE
TECHNOLOGIES, INC.